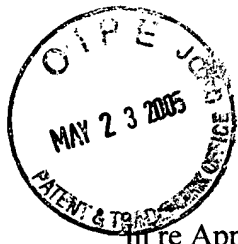


Rfw



Attorney Docket no: 0553-0193.01

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Takayama et al.

Serial No.: 10/672,521

Filed: September 26, 2003

For: Wiring Material, Semiconductor Device
Provided With A Wiring Using The Wiring
Material And Method of Manufacturing
Thereof

Examiner: Ha T. Nguyen

Art Unit: 2812

Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

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May 19, 2005
(Date of Deposit)

Shannon Wallace

Name of applicant, assignee, or Registered Rep.

Shannon Wallace 5/19/05
Signature Date

AMENDMENT B

In response to the Office Action dated February 22, 2005, please amend the above-identified application as follows: